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N-Channel MOSFET

# Lonten N-channel 650V, 47A, 0.07Ω LonFET<sup>™</sup> Power MOSFET

#### Description **Product Summary** LonFET<sup>™</sup> Power MOSFET is fabricated using V<sub>DS</sub> @ T<sub>i.max</sub> 700V advanced super junction technology. The resulting 0.070Ω R<sub>DS(on).max</sub> device has extremely low on resistance, making it 141A I<sub>DM</sub> especially suitable for applications which require 87nC Q<sub>g,typ</sub> superior power density and outstanding efficiency. **Features** TO-247 Ultra low R<sub>DS(on)</sub> ٠ Ultra low gate charge (typ. $Q_q = 87nC$ ) ٠ D 100% UIS tested ٠ **RoHS** compliant • G

## **Applications**

- Power faction correction (PFC).
- Switched mode power supplies (SMPS).
- Uninterruptible power supply (UPS).

# Absolute Maximum Ratings Parameter

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	650	V
Continuous drain current ( $T_c = 25^{\circ}C$ )	ID	47	А
( T <sub>c</sub> = 100°C )		30	А
Pulsed drain current <sup>1)</sup>	I <sub>DM</sub>	141	А
Gate-Source voltage	V <sub>GSS</sub>	±30	V
Avalanche energy, single pulse 2)	E <sub>AS</sub>	1200	mJ
Power Dissipation TO-247 ( $T_c = 25^{\circ}C$ )	P	290	W
- Derate above 25°C	P <sub>D</sub>	2.32	W/°C
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C
Continuous diode forward current	Is	47	A
Diode pulse current	I <sub>S,pulse</sub>	141	A

# Thermal Characteristics TO-247

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	0.43	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	60	°C/W
Soldering temperature, wavesoldering only allowed	т	260	°C
at leads. (1.6mm from case for 10s)	I sold	200	U



# Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube	Units/Real
LSB65R070GF	TO-247	LSB65R070GF	30	

# **Electrical Characteristics** T<sub>c</sub> = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics			·			•
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =0.25 mA	650	-	-	V
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_D=0.25mA$	2	3	4	V
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> =650 V, V <sub>GS</sub> =0 V,				μA
		$T_j = 25^{\circ}C$	-	-	1	
		$T_j = 125^{\circ}C$	-	10	-	
Gate leakage current, Forward	I <sub>GSSF</sub>	$V_{GS}$ =30 V, $V_{DS}$ =0 V	-	-	50	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-30 V, V <sub>DS</sub> =0 V	-	-	-50	nA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =23.5 A	-			
		$T_j = 25^{\circ}C$	-	0.062	0.070	Ω
		$T_j = 150^{\circ}C$	-	0.16	-	
Dynamic characteristics						
Input capacitance	C <sub>iss</sub>	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	-	4677	-	
Output capacitance	C <sub>oss</sub>	f = 1 MHz	-	2556	-	pF
Reverse transfer capacitance	C <sub>rss</sub>		-	30	-	
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD} = 400V, I_D = 23.5A$	-	28.3	-	
Rise time	tr	$R_G = 10\Omega, V_{GS}=10V$	-	12.9	-	ns
Turn-off delay time	t <sub>d(off)</sub>		-	186.5	-	
Fall time	t <sub>f</sub>		-	13.5	-	
Gate charge characteristics						
Gate to source charge	Q <sub>gs</sub>	V <sub>DD</sub> =480 V, I <sub>D</sub> =23.5A,	-	24	-	
Gate to drain charge	Q <sub>gd</sub>	V <sub>GS</sub> =0 to 10 V	-	31.24	-	nC
Gate charge total	Qg		-	87	-	
Gate plateau voltage	V <sub>plateau</sub>		-	5.5	-	V
Reverse diode characteristics						
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0 V, I <sub>F</sub> =23.5A	-	1.0	-	V
Reverse recovery time	t <sub>rr</sub>	V <sub>R</sub> =50 V, I <sub>F</sub> =47A,	-	243.5	-	ns
Reverse recovery charge	Qrr	dl <sub>F</sub> /dt=100 A/µs	-	1.9	-	μC
Peak reverse recovery current	Irrm		-	14.0	-	А

Notes:

1. Limited by maximum junction temperature, maximum duty cycle is 0.75.

2.  $I_{AS} = 8A$ ,  $V_{DD} = 60V$ , Starting  $T_j = 25^{\circ}C$ .



# **Electrical Characteristics Diagrams**

Figure 1. On-Region Characteristics

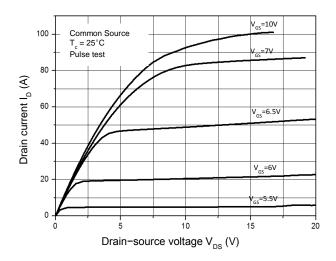


Figure 3. On-Resistance Variation vs. Drain Current

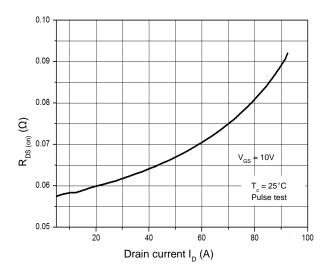


Figure 5. Breakdown Voltage vs. Temperature

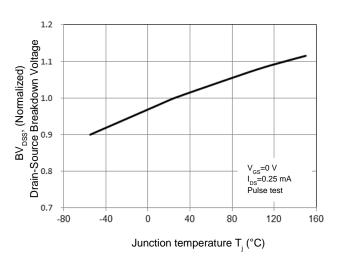


Figure 2. Transfer Characteristics

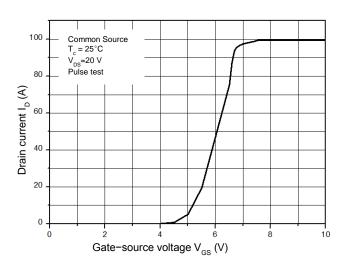
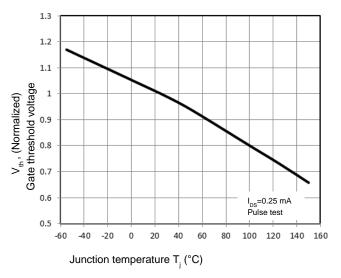
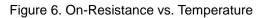
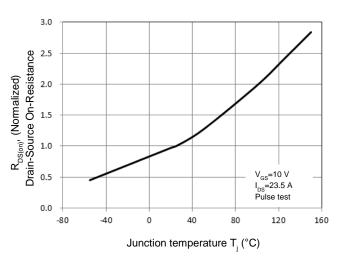


Figure 4. Threshold Voltage vs. Temperature









#### Figure 7. Capacitance Characteristics

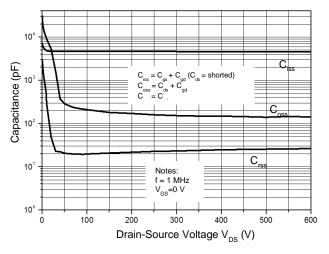


Figure 9. Maximum Safe Operating Area

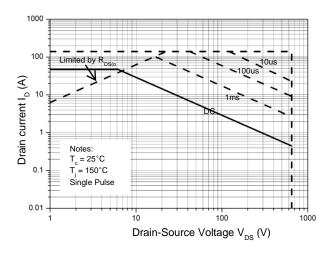


Figure 8. Gate Charge Characterist

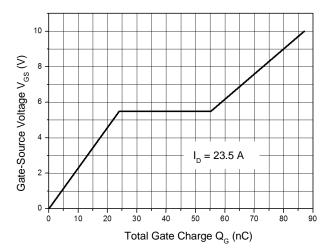
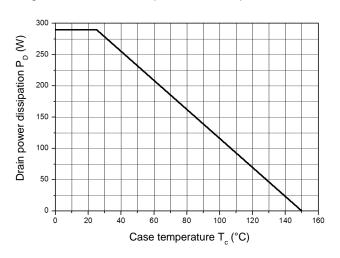
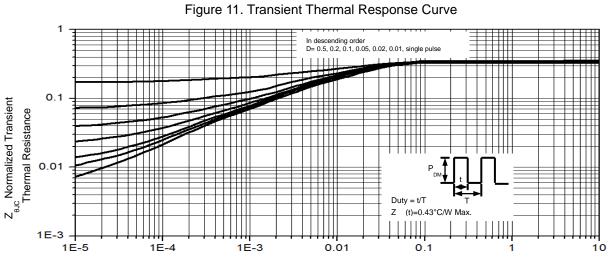


Figure 10. Power Dissipation vs. Temperature

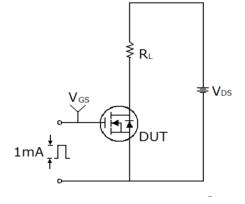


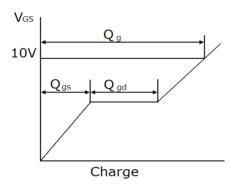


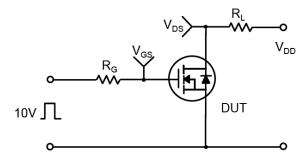
Pulse Width t (s)

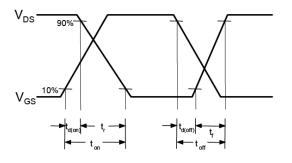


### Gate Charge Test Circuit & Waveform

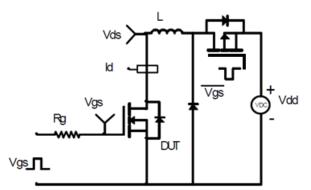


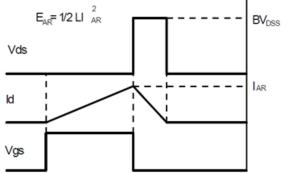






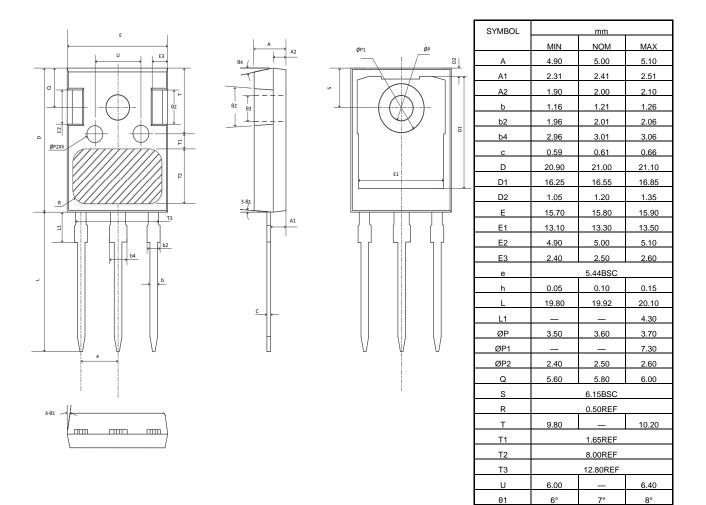
**Unclamped Inductive Switching Test Circuit & Waveforms** 



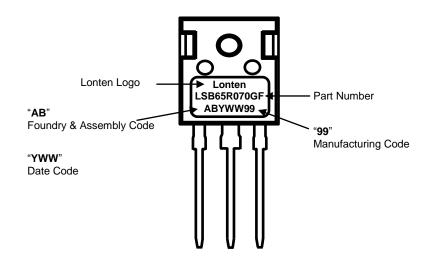




#### **Mechanical Dimensions for TO-247**



### **TO-247 Part Marking Information**



θ2

θ3

θ4

4°

1°

14°

5°

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15°

6°

1.5°

16°



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